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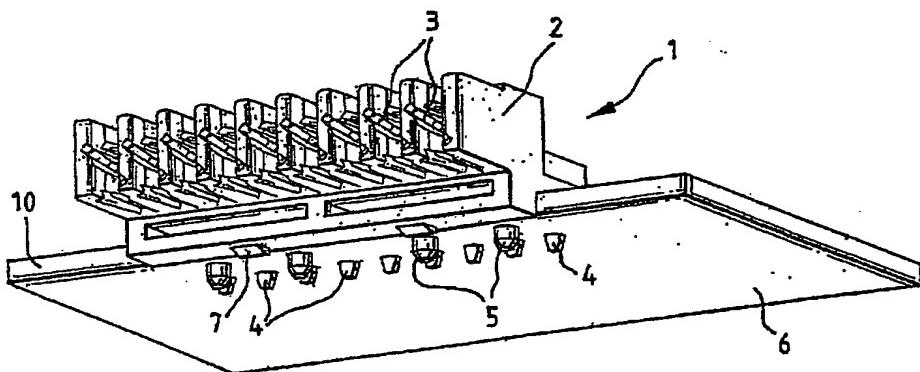
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(54) Title: CONDUCTOR CONNECTING MODULE FOR PRINTED CIRCUIT BOARDS

(54) Bezeichnung: ADERANSCHLUSSMODUL FÜR LEITERPLATTEN



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(57) Abstract: The invention relates to a conductor connecting module (1) for printed circuit boards, comprising a housing (2) in which contact elements are disposed. Said contact elements have a first contact area that is configured as an insulation displacement contact (3), and a second contact area that is configured as a solderable contact pin (4). The contact pins (4) are disposed at a right angle to the insulation displacement contacts (3) so that the insulation displacement contacts (3), in the mounted state, lie in a plane parallel to the printed circuit board (6).

(57) Zusammenfassung: Die Erfindung betrifft ein Aderanschlussmodul (1) für Leiterplatten, umfassend ein Gehäuse (2), in dem Kontakttelemente angeordnet sind wobei die Kontakttelemente einen ersten Kontaktbereich aufweisen, der als Schneid-Klemm-Kontakt (3) ausgebildet ist, und einen zweiten Kontaktbereich aufweisen, der als lötbarer Kontaktpin (4) ausgebildet ist, wobei die Kontaktpins (4) in einem rechten Winkel zu den Schneid-Klemm-Kontakten (3) angeordnet sind, so dass die Schneid-Klemm-Kontakte (3) im montierten Zustand in einer Ebene parallel zur Leiterplatte (6) liegen.

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